



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH1R06U	HNZJ*F62B81B	A	ZA41	2018-03-14
Amount		UoM	Unit type	ST ECOPACK Grade
98		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	61
Lead	2.15	Soft solder	21908

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNZJ*F62B81B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.823	mg	supplier	die	Silicon (Si)	7440-21-3		0.789	mg	958688	8051
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	8505	71
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	3647	31
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	7290	61
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	7290	61
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	7290	61
Leadframe & Clip	Copper and its alloy	40.856	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		40.836	mg	999510	416694
				Supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	49	20
				Supplier	Alloy	Iron (Fe)	7439-89-6		0.004	mg	98	41
				Supplier	Alloy	Iron Phosphide(FeP)	26508-33-8		0.014	mg	343	142
Die attach	Other organic material	2.321	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.058	mg	24989	592
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.116	mg	49979	1184
				JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.147	mg	925032	21908
Encapsulation	Other organic material	53.061	mg	Supplier	Molding Compound	silica fused	7631-86-9		39.263	mg	739960	400643
				Supplier	Molding Compound	silica quartz	14808-60-7		10.612	mg	199996	108286
				Supplier	Molding Compound	phenolic resin	9003-35-4		2.654	mg	50018	27082
				Supplier	Molding Compound	carbon black	1333-86-4		0.532	mg	10026	5429
Finishing	Other inorganic material	0.939	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		0.939	mg	1000000	9582